

#5/5490 11/2/0 PATENT /

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Pai-Hung Pan

Serial No.: 09/944,506

**Filed:** August 30, 2001

For: TECHNIQUE FOR FORMING SHALLOW TRENCH ISOLATION STRUCTURE WITHOUT CORNER EXPOSURE AND RESULTING

**STRUCTURE** 

Confirmation No.: 4348

Examiner: Unknown

Group Art Unit: 2823

**Attorney Docket No.:** 2919.5US (96-499.2)

CERTIFICATE OF MAILING

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November 11, 2002 Date

Amanda Holland

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## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Box NON-FEE Commissioner for Patents Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an

admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56(b) exists.

## DOCUMENTS

## Other Documents

Lee, H., et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)," IEEE Symposium on VLSI Technology 1996, pp. 158-159.

Applicant offers to supply any explanation or discussion of the documents that the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. § 1.17(p) is required.

Respectfully submitted,

Brick G. Power

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Enclosures: Form PTO/SB/08

Cited Document

Document in ProLaw

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Substitute	bstitute for form 1449A/PTO		Complete if Known		
INFORMATION DISCLOSURE			Application Number	09/944,506	
			Filing Date	August 30, 2001	
STATEMENT BY APPLICANT		First Named Inventor	Pai-Hung Pan		
			Group Art Unit	2823	
(use as many sheets as necessary)		Examiner Name	Unknown		
Sheet	1	of 1	Attorney Docket Number	2919 5US (96-499 2)	

Examiner Initials *	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		
		Lee, H., et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)," IEEE Symposium on VLSI Technology 1996, pp. 158-159.		
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<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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<sup>&</sup>lt;sup>1</sup> Unique citation designation number (optional). <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached.